

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Teppei HIROTSU</td> <td>11/20/2012</td> </tr> <tr> <td>Nobuyasu KANEKAWA</td> <td>11/20/2012</td> </tr> <tr> <td>Itaru TANABE</td> <td>11/21/2012</td> </tr> </tbody> </table>		Name	Execution Date	Teppei HIROTSU	11/20/2012	Nobuyasu KANEKAWA	11/20/2012	Itaru TANABE	11/21/2012
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RECEIVING PARTY DATA									
<table border="1"> <tr> <td>Name:</td> <td>Hitachi Automotive Systems, Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>2520, Takaba</td> </tr> <tr> <td>City:</td> <td>Hitachinaka-shi, Ibaraki</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> </table>		Name:	Hitachi Automotive Systems, Ltd.	Street Address:	2520, Takaba	City:	Hitachinaka-shi, Ibaraki	State/Country:	JAPAN
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PROPERTY NUMBERS Total: 1									
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CORRESPONDENCE DATA									
<p>Fax Number: 2026288844  <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 2026242500        Email: Galemousavi@crowell.com        Correspondent Name: Crowell &amp; Moring LLP        Address Line 1: P.O. Box 14300        Address Line 4: Washington, DISTRICT OF COLUMBIA 20044-4300</p>									
ATTORNEY DOCKET NUMBER:	106734.65160US								
NAME OF SUBMITTER:	Michael H. Jacobs								
<p>Total Attachments: 1        source=65160US_Assignment#page1.tif</p>									

OP \$40.00 13807278

# ASSIGNMENT ( 譲渡証 )

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me by Hitachi Automotive Systems, Ltd., a corporation organized under the laws of Japan, located at 2520, Takaba, Hitachinaka-shi, Ibaraki Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi Automotive Systems, Ltd., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

## CURRENT CONTROL SEMICONDUCTOR ELEMENT AND CONTROL DEVICE USING THE SAME

invented by me (if only one is named below ) or us (if plural inventors are named below ) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi Automotive Systems, Ltd., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi Automotive Systems, Ltd.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)  
(発明者フルネームサイン)

Date Signed  
(署名日)

1) Teppei Hirotzu Teppei HIROTSU

11/20/2012

2) Nobuyasu Kanekawa Nobuyasu KANEKAWA

11/20/2012

3) Itaru Tanabe Itaru TANABE

11/21/2012

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